

Specifications

Insulation Resistance:	1,000MΩ min. at 100V DC
Dielectric Withstanding Voltage:	100V AC for 1 minute
Contact Resistance:	100mΩ max. at 10mA/20mV max.
Operating Temperature Range:	-40°C to +150°C
Contact Force:	58.8mN (6gf) per pin approx.
Actuation Force:	29.6N (3kg)

Materials and Finish

Housing: Polyetherimide (PEI), glass-filled  
Polyethersulphone (PES), glass-filled  
Contacts: Beryllium Copper (BeCu)  
Plating: Gold over Nickel

Features

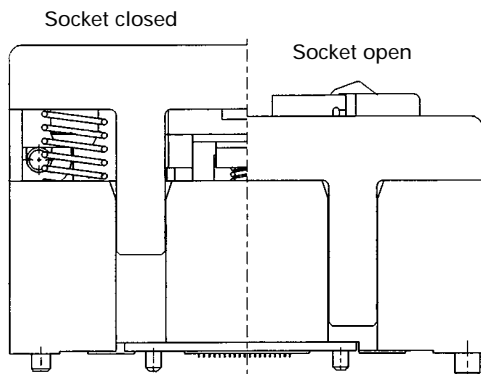
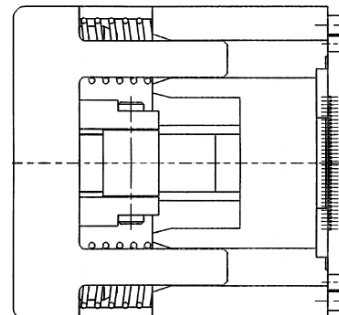
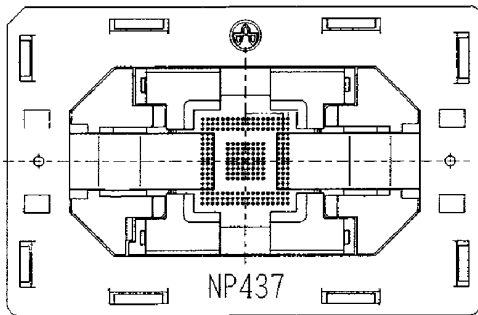
Open top socket for BGA / LGA / CSP packages with 0.4mm pitch.  
22 x 22 maximum grid size and 11 x 11 maximum body size  
Depopulation versions available  
Compression mount 0.4 to 0.6mm fan-out type

Part Number (Details)

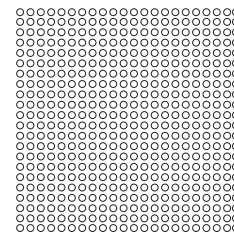
Please Contact Yamaichi



Outline Socket Dimensions

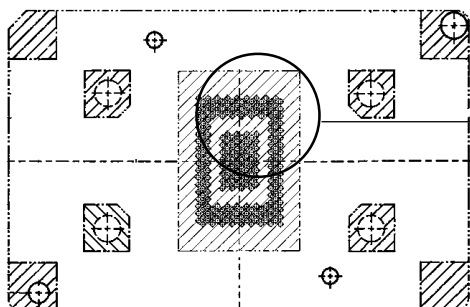


Typical IC Grid Size 22 x 22 (max.)



Typical PCB Layout

Top View from Socket



Detail of Fan-out type

